

MRD 5-24-99

ATTY. DOCKET NO: AB-729 US

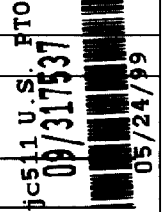
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To the Honorable Commissioner of Patents and Trademarks, 101057990, all documents or copy thereof.



1. Name of conveying party(ies):

- (a) Do Soo Jeong
- (b) Hai Jeong Sohn
- (c) Dong Ho Lee

Additional name(s) of conveying party(ies) attached?

Yes No

2. Name and address of receiving party(ies):

Name: Samsung Electronics Co., Ltd.

Internal Address: _____

Street Address: 416 Maetan-dong, Paldal-ku, Suwon-city

City Kyungki-do Country Republic of Korea ZIP _____

Additional name(s) & address(es) attached? Yes No

3. Nature of Conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other _____

Execution Date: 04/28/99 and 04/29/99

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 04/28/99 and 04/29/99

A. Patent Application No.(s) -

Title: Method For Manufacturing A Chip Scale Package

09/317537

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Don C. Lawrence

Internal Address: SKJERVEN, MORRILL, MacPHERSON,

FRANKLIN & FRIEL LLP

Street Address: 25 METRO DRIVE, SUITE 700

City SAN JOSE State CA ZIP 95110

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

- Authorized to be charged to Deposit Account 19-2386 ✓
- Charge Deposit Account 19-2386 for any additional fees required for this conveyance and credit deposit account 19-2386 any amounts overpaid

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8. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Don C. Lawrence Reg. No. 31,975
Name of Person Signing

Don C. Lawrence
Signature

5/24/99
Date

Total number of pages comprising cover sheet: 2

ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we

Do Soo Jeong	of	No. 2-411, Samsung 1st Apt. Maetan-4-dong, Paldal-ku, Suwon-city Kyungki-do, Republic of Korea
Hai Jeong Sohn	of	No. 4-1410, Imkwang Apt. Maetan-3-dong, Paldal-ku, Suwon-city Kyungki-do, Republic of Korea
Dong Ho Lee	of	No. 209-707, Shinbanpo 4th Apt. Jamwon-dong, Seocho-ku Seoul, Republic of Korea

hereby sell, assign and transfer to Samsung Electronics Co., Ltd., a Republic of Korea corporation, having a place of business at 416, Maetan-dong, Paldal-ku, Suwon-city, Kyungki-do, Republic of Korea, its successors and assigns, the entire right, title and interest throughout the world in our invention in

Method For Manufacturing A Chip Scale Package

for which we have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, their successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 28 day of April, 1999.

Do Soo Jeong
Do Soo Jeong

Executed this 29 day of April, 1999.

Hai Jeong Sohn
Hai Jeong Sohn

Executed this 28 day of April, 1999.

Dong Ho Lee
Dong Ho Lee